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#### **DUAL P-CHANNEL ENHANCEMENT MODE MOSFET**

#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D MAX</sub> T <sub>A</sub> = +25°C
-20V	$90m\Omega$ @ $V_{GS} = -4.5V$	-3.2A
-20V	$137m\Omega @ V_{GS} = -2.5V$	-2.6A

### **Description**

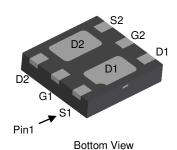
This MOSFET is designed to minimize on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## **Applications**

- Load Switch
- Power Management Functions
- Portable Power Adaptors

#### U-DFN2020-6



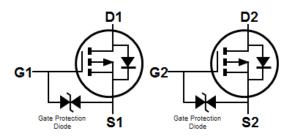


## **Features**

- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Max Height
- . ESD protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound;
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe; Solderable per MIL-STD-202, Method 208
- Terminals Connections: See Diagram Below
- Weight: 0.0065 grams (Approximate)



Q1 P-CHANNEL MOSFET Q2 P-CHANNEL MOSFET Internal Schematic

# **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMP2060UFDB -7	U-DFN2020-6	3,000/Tape & Reel
DMP2060UFDB -13	U-DFN2020-6	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**

U-DFN2020-6



FD = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Key

Year	2014	4	2015		2016	20	17	2018		2019	2	2020
Code	В		С		D	[		F		G		Н
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	-20	V		
Gate-Source Voltage		$V_{GSS}$	±12	V	
Continuous Drain Current (Note 5) $V_{GS} = 4.5V$ Steady $T_A = +25^{\circ}C$ $T_{A} = +70^{\circ}C$				-3.2 -2.5	Α
Maximum Continuous Body Diode Forward Current (Note 5)	Is	-1.5	Α		
Pulsed Drain Current (10μs pulse, duty cycle = 1%)	I <sub>DM</sub>	-18	Α		

# **Thermal Characteristics**

Characteristic		Symbol	Value	Units	
Total Power Discinction (Note 5)	Steady State	ם	1.4	W	
Total Power Dissipation (Note 5)	t < 5s	P <sub>D</sub>	2.2	VV	
Thermal Penistance, Junction to Ambient (Note 5)	Steady State	ם	92		
Thermal Resistance, Junction to Ambient (Note 5)	t < 5s	$R_{\theta JA}$	55	°C/W	
Thermal Resistance, Junction to Case (Note 5)	$R_{ heta JC}$	30			
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to 150	°C	

# Electrical Characteristics P-CHANNEL (@T<sub>A</sub> = +25°C, unless otherwise specified.)

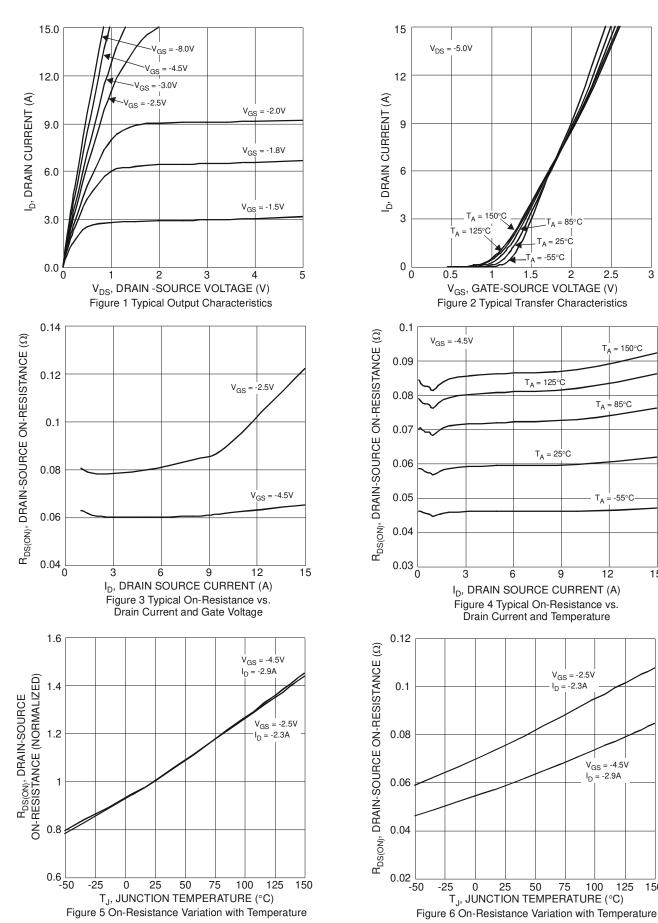
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage		-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	-1.0	μA	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.35	_	-1.4	V	$V_{DS}=V_{GS},\ I_D=-250\mu A$	
Static Drain-Source On-Resistance	D	_	59	90	mΩ	$V_{GS} = -4.5V, I_D = -2.9A$	
Static Dialif-Source Off-Nesistance	R <sub>DS(ON)</sub>	_	76	137	11122	$V_{GS} = -2.5V$ , $I_D = -2.3A$	
Diode Forward Voltage	$V_{SD}$	_	-0.65	-1.2	V	$V_{GS} = 0V, I_{S} = -3.0A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C <sub>iss</sub>	_	881	_	pF	10,4,5,4	
Output Capacitance	Coss	_	84	_	pF	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	$C_{rss}$	_	67	_	pF	1 – 1.0WH12	
Gate Resistance	$R_g$	_	14.3	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)		_	11	_	nC		
Total Gate Charge (V <sub>GS</sub> = -8V)	Qg	_	18	_	nC	V <sub>DS</sub> = -10V. In = -3.7A	
Gate-Source Charge	$Q_{gs}$	_	1.5	_	nC	$V_{DS} = -10V, I_{D} = -3.7A$	
Gate-Drain Charge	$Q_{gd}$	_	2.3	_	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	_	5.0	_	ns		
Turn-On Rise Time	t <sub>r</sub>	_	9.5	_	ns	$V_{DD} = -10V, V_{GS} = -4.5V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	29.7	_	ns	$R_L = 3.3\Omega, R_G = 1\Omega$	
Turn-Off Fall Time	tf	_	20.4	_	ns		
Body Diode Reverse Recovery Time	trr	_	23.6	_	nS	$I_S = -3.0A$ , $dI/dt = 100A/\mu s$	
Body Diode Reverse Recovery Charge	Qrr	_	11.4	_	nC	$I_S = -3.0A$ , $dI/dt = 100A/\mu s$	

 Device mounted on on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
 Short duration pulse test used to minimize self-heating effect
 Guaranteed by design. Not subject to product testing. Notes:

3

15







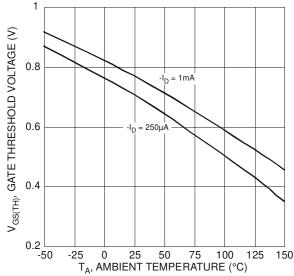
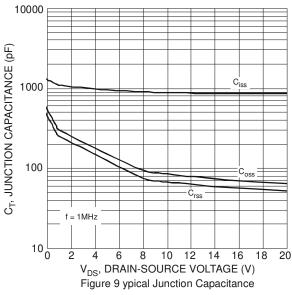
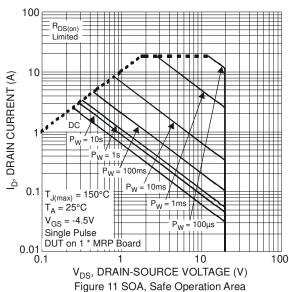
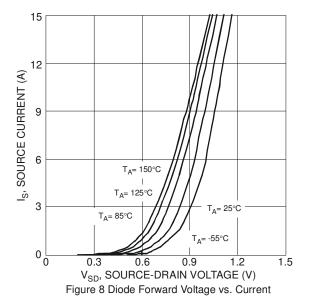
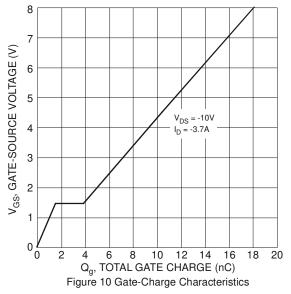


Figure 7 Gate Threshold Variation vs. Ambient Temperature

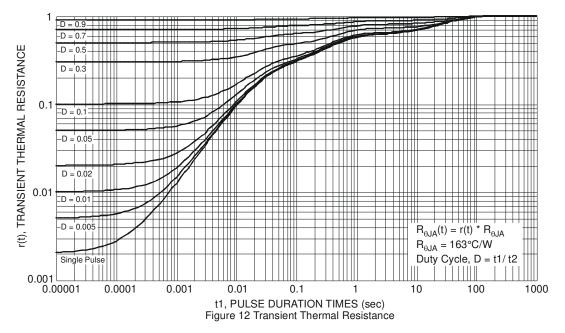






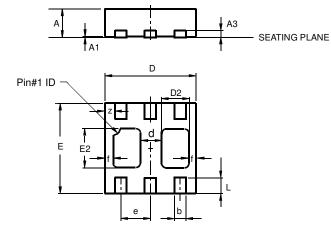






## **Package Outline Dimensions**

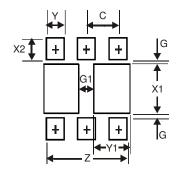
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



U-DFN2020-6							
Type B							
Dim	Min	Max	Тур				
Α	0.545	0.605	0.575				
<b>A</b> 1	0	0.05	0.02				
A3	_	_	0.13				
b	0.20	0.30	0.25				
D	1.95	2.075	2.00				
d	_	_	0.45				
D2	0.50	0.70	0.60				
e			0.65				
Е	1.95	2.075	2.00				
E2	0.90	1.10	1.00				
f			0.15				
L	0.25	0.35	0.30				
Z			0.225				
All Dimensions in mm							

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
Z	1.67			
G	0.20			
G1	0.40			
X1	1.0			
X2	0.45			
Υ	0.37			
Y1	0.70			
С	0.65			



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